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— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

[Continued on next page]

(54) Title: METHOD AND APPARATUS OF HALOGEN REMOVAL

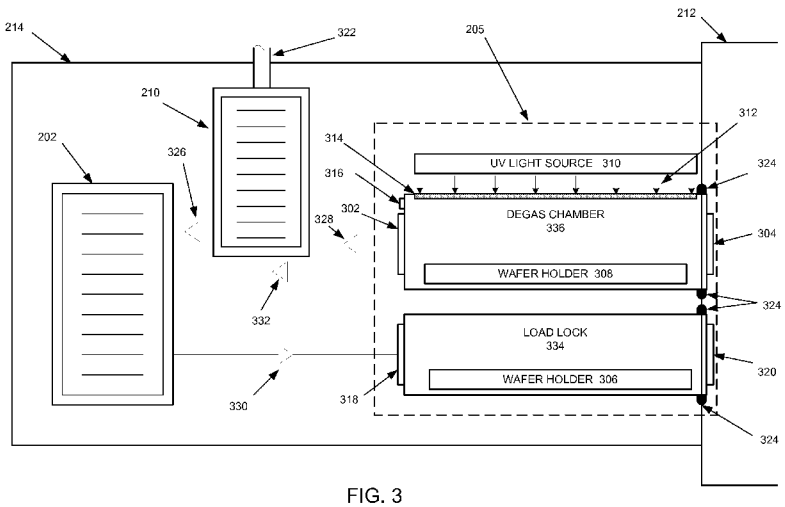


FIG. 3

(57) Abstract: A wafer is provided into an entrance load lock chamber. A vacuum is created in the entrance load lock chamber. The wafer is transported to a processing tool. The wafer is processed in a process chamber to provide a processed wafer, wherein the processing forms halogen residue. A degas step is provided in the process chamber after processing the wafer. The processed wafer is transferred into a degas chamber. The processed wafer is treated in the degas chamber with UV light and a flow of gas comprising at least one of ozone, oxygen, or H_2O. The flow of gas is stopped. The UV light is stopped. The processed wafer is removed from the degas chamber.

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